

THERMAL INTERFACE ADHESIVE AND REWORK

Abstract

A reworkable conductive adhesive composition, and method of making such, comprising an epoxy based conductive adhesive containing conductive metal filler particles dispersed in a solvent-free hybrid epoxy polymer matrix. In an additional embodiment an improved method of removing cured conductive polymer adhesives, disclosed here as thermal interface materials, from electronic components for reclamation or recovery of usable parts of module assemblies, particularly high cost semiconductor devices, heat sinks and other module components.